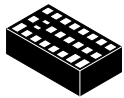


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

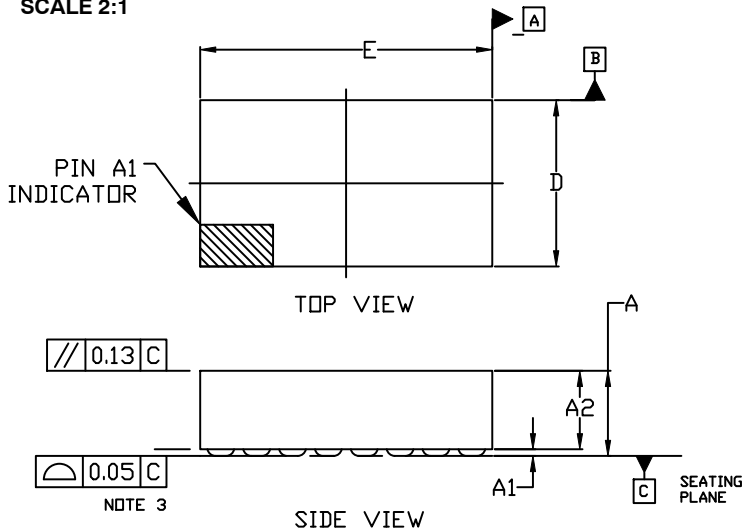
ON Semiconductor®



SCALE 2:1

SIP25, 5.59x3.18  
CASE 127DN  
ISSUE A

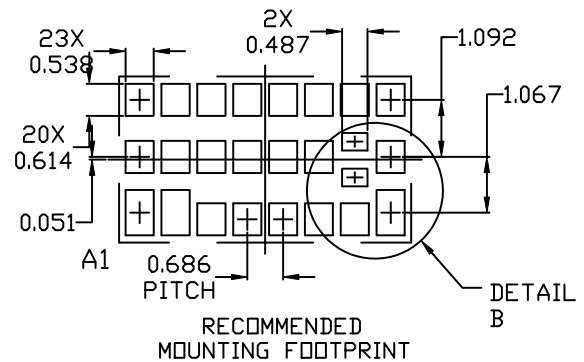
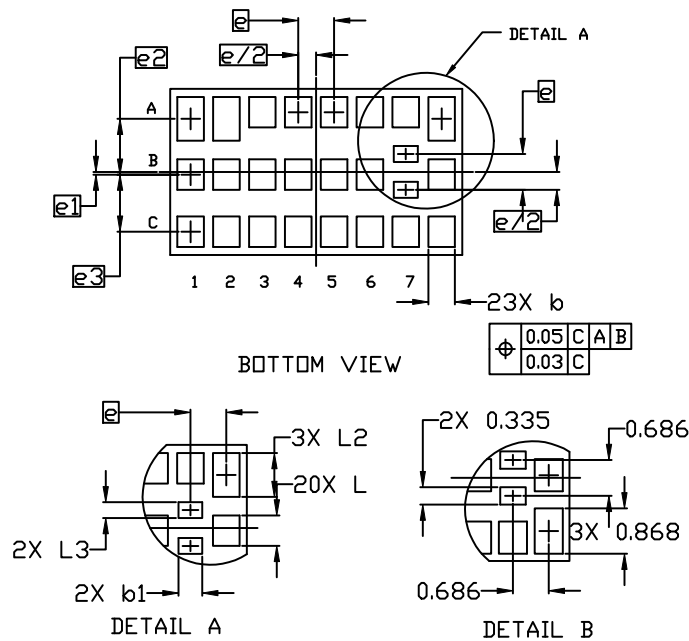
DATE 21 JUL 2020



NOTES:

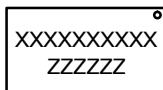
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE PADS.

DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	---	---	1.68
A1	0.08	0.13	0.18
A2	---	---	1.50
b	0.478	0.508	0.538
b1	0.427	0.457	0.487
D	3.05	3.18	3.31
E	5.46	5.59	5.72
e	0.686 BSC		
e1	0.051 BSC		
e2	1.067 BSC		
e3	1.092 BSC		
L	0.554	0.584	0.614
L2	0.808	0.838	0.868
L3	0.275	0.305	0.335



\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM\*



XX = Specific Device Code  
ZZ = Lot Traceability

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	SIP25, 5.59x3.18	PAGE 1 OF 1

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